



Product Change Notification

113148 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113148 - 00
Change Title: Intel RAID Maintenance Free Backup Unit
AXXRMFBU4
PCN 113148-00, Product Design, Order Code
Update Gas Gauge Firmware, New retention
bracket, Cable sleeves, Connector and Order
Code
Date of Publication: July 18, 2014

Key Characteristics of the Change:

Product Design, Order Code

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Sept 17, 2014
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following changes on the Intel RAID Maintenance Free Backup Unit AXXRMFBU4.

1. Update the Gas Gauge Firmware and change the current connector to a stronger solution on the Transportable Flash Memory (TFM) Module.
2. Replace the current retention bracket with a redesigned, more robust solution.
3. Replace the current cable sleeves with a more robust cable sleeve solution.
4. Order Code is changing.

Customer Impact of Change and Recommended Action:

Intel does not foresee any adverse customer impact from this change. Standard level evaluation may be performed as deemed necessary.

Customers will need to place future orders using the new Order Code (Post Change MM#) as noted in below table.

Products Affected / Intel Ordering Codes:

Product Code	Pre Change MM#	Post Change MM#
AXXRMFBU4	929734	937318

PCN Revision History:

Date of Revision:

July 18, 2014

Revision Number:

00

Reason:

Originally Published PCN